



#5/4-4-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/881,299
Filing Date June 13, 2001
Inventor Dinesh Chopra, et al
Assignee Micron Technology, Inc.
Group Art Unit 2825
Examiner P. Cao
Attorney's Docket No. MI22-1247
Title: Conductive Connection Forming Methods, Oxidation Reducing Methods, and Integrated Circuits Formed Thereby

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INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. §§ 1.56, 1.97 AND 1.98

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. No admission is made regarding whether all the submitted references are prior art.

The listed references were cited by, or submitted to, the Office in the parent, co-pending application of the above-identified application. The above-identified application is a divisional application of co-pending application Serial No. 09/518,511, filed March 3, 2000. Such prior disclosure is sufficient for the above-identified application as far as copies of the references are concerned. 37 C.F.R. § 1.98(d) and MPEP § 609(2).

Citation of these references is respectfully requested.

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Respectfully submitted,

Dated: 21 Feb 2002

By: James E. Lake
James E. Lake
Reg. No. 44,854

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